

Material Content Data Sheet								
Sales Product Name	IM12B10CC1			**Issued**		25. March 2024		
MA#	MA006034962							
Package	PG-MDIP-24-61			**Weight:**		6907.53 mg		
Construction Element	**Material group**	Materials	**CAS if applicable**	**Weight [mg]**	**Average mass [%]**	**Sum [%]**	**Average mass [ppm]**	**Sum [ppm]**
chip_01	inorganic material	silicon	7440-21-3	6.694	0.10	0.10	969	969
chip_02	inorganic material	silicon	7440-21-3	2.617	0.04	0.04	379	379
chip_03	inorganic material	silicon	7440-21-3	2.617	0.04	0.04	379	379
chip_04	inorganic material	silicon	7440-21-3	2.617	0.04	0.04	379	379
chip_05	inorganic material	silicon	7440-21-3	2.617	0.04	0.04	379	379
chip_06	inorganic material	silicon	7440-21-3	2.617	0.04	0.04	379	379
chip_07	inorganic material	silicon	7440-21-3	2.617	0.04	0.04	379	379
chip_08	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_09	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_10	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_11	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_12	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
chip_13	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	199	199
leadframe	non noble metal	copper	7440-50-8	1301.249	18.84	18.84	188380	188380
wire	noble metal	gold	7440-57-5	0.756	0.01		109	
	non noble metal	aluminium	7429-90-5	36.537	0.53	0.54	5289	5398
encapsulation	organic material	carbon black	1333-86-4	30.727	0.44		4448	
	plastics	epoxy resin	-	384.091	5.56		55604	
	inorganic material	silicondioxide	60676-86-0	3426.096	49.61	55.61	495992	556044
leadfinish	non noble metal	tin	7440-31-5	41.697	0.60	0.60	6036	6036
plating	non noble metal	nickel	7440-02-0	0.914	0.01	0.01	132	132
solder	non noble metal	antimony	7440-36-0	0.585	0.01		85	
	noble metal	silver	7440-22-4	1.463	0.02		212	
	non noble metal	tin	7440-31-5	3.803	0.06	0.09	551	848
glue	plastics	acrylic resin	-	0.249			36	
	plastics	maleimide resin	-	0.249			36	
	inorganic material	silicondioxide	60676-86-0	0.647	0.01		94	
	noble metal	silver	7440-22-4	0.746	0.01		108	
	plastics	epoxy resin	-	0.971	0.01	0.03	141	415
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	noble metal	silver	7440-22-4	0.030			4	
	organic material	ethyl cellulose	9004-57-3	0.024			4	
	organic material	DEGBE	112-34-5	0.105			15	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			29	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		83	
	inorganic material	manganesedioxide	1313-13-9	0.658	0.01	0.02	95	236
pcb metal	non noble metal	copper	7440-50-8	21.446	0.31	0.31	3105	3105
pcb plastic	plastics	epoxy resin	-	105.646	1.53		15294	
	inorganic material	glass fibre wool	65997-17-3	129.123	1.87	3.40	18693	33987
pcb plating	noble metal	gold	7440-57-5	0.066			10	
	non noble metal	nickel	7440-02-0	3.029	0.04	0.04	439	449
dcb ceramic	inorganic material	alumina	1344-28-1	723.354	10.47	10.47	104719	104719
dcb metal	non noble metal	copper	7440-50-8	661.840	9.58	9.58	95814	95814
deviation	< 10%				Sum in total:	100.00		1000000

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